

Product/process change notification

PCN N° 2021-181-A

Dear customer,

Please find attached our Infineon Technologies AG PCN:

Capacity extension by introduction of 300mm wafer diameter for BSC074N15NS5 (OptiMOS™5) product in PG-TSON-8 package at Infineon Technologies Dresden, Germany

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **2022-01-13**
- Infineon aligns with the widely recognized JEDEC STANDARD “**JESD46**“, which stipulates: “**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress.
We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.
For further details, please visit our website:
<https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/>

Infineon Technologies AG
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Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Constanze Hufenbecher, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

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► **Products affected**

Please refer to attached affected product list 1_cip21181_a

► **Detailed change information**

Subject

Introduction of 300mm wafer diameter at Infineon Technologies Dresden GmbH

Reason

Next phase of Front-End capacity expansion by introduction of 300mm wafer diameter to support continuous increasing customer demand.

Description

Wafer Production Site & Wafer test

<u>Old</u>	<u>New</u>
<ul style="list-style-type: none"> Infineon Technologies Austria AG, Villach, Austria (200mm) 	<ul style="list-style-type: none"> Infineon Technologies Austria AG, Villach, Austria (200mm) <i>and</i> Infineon Technologies Dresden GmbH, Germany (300mm)
<p>Wafer lot number</p> <ul style="list-style-type: none"> VExxxxxx (Villach, 200mm) 	<ul style="list-style-type: none"> VExxxxxx (Villach,200mm) <i>and</i> ZFxxxxxx (Dresden,300mm)

► **Product identification**

External traceability assured via waferlot number & country of diffusion on product label

► **Impact of change**

NO change on electrical, thermal parameters and reliability as proven via product qualification and characterization.

NO change in existing datasheet parameters

NO change in quality and reliability. Processes are optimized to meet product performance according to already applied Infineon specification

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► Attachments

1_cip21181_a	affected product list
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► Time schedule

- | | |
|------------------------------|------------|
| ■ Final qualification report | on request |
| ■ First samples available | on request |
| ■ Intended start of delivery | 2022-03-01 |

If you have any questions, please do not hesitate to contact your local sales office.



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Capacity extension by introduction of 300mm wafer diameter for BSC074N15NS5 (OptiMOS™5) product in PG-TSON-8 package at Infineon Technologies Dresden, Germany

Sales name	SP number	OPN	Package
BSC074N15NS5	SP004419136	BSC074N15NS5ATMA1	PG-TSON-8